

KEMKO® 175 ClearSEAL

Epoxy Adhesive for
Crack Sealing or
General Bonding

- Type:** Two-component, solvent-free, non-sag, epoxy paste resin / hardener.
- Primary Use:** Surface sealing of cracks and delaminations in rigid construction materials in preparation for repair by pressure injection grouting.
General use bonding adhesive for rigid construction materials.
- Substrates:** Concrete, masonry, stone (dry, damp or wet), steel and sealed wood.
- Minimum Temp:** Installation: 40° F, Cure: 40° F (substrate temperature).
- Color:** Opaque white, (clear in thin sections).
- Coverage:** 200 - 350 lineal feet/gallon (approx.) in crack sealing applications
- Shelf Life:** Three years minimum in sealed containers (see below for conditions).

The properties listed in this bulletin are typical and descriptive of the product and should not be used for specification purposes. For specification preparation, reference the specification of this product available from ChemCo Systems, Inc. This product is available only through KIP System (KEMKO® Injection Process)

Description: KEMKO® 175, ClearSEAL is a two-component, non-sag, epoxy paste adhesive designed for sealing cracks and delaminations in concrete, masonry, stone, steel and sealed wood. In preparation repair with KIP System pressure injection grouting. It also may be used as a bonding adhesive for most rigid construction materials and is ideally suited for bonding applications in cool and cold environments. KEMKO 175 bonds to dry, damp and wet (no free standing water) substrates and can be applied up to 1/2 inch thick without sag or flow. The components do not contain volatile organic compounds (VOC's).

Features: When used as a cap seal over cracks prior to epoxy injection, the translucent quality of this product permits technicians to visually track the progress of injection epoxy along the face of the crack. The low temperature reactivity of KEMKO 175 makes it ideally suited for crack sealing on cool and cold substrates where thin film high strength and hardness are required and when an extended low temperature cure time is not a constraint. The product has sufficient working life for use as a crack sealer or bonding adhesive at moderate substrate temperatures. It has a convenient 2:1 (by vol.) mixing ratio and is formulated for similar A and B component viscosities for ease of mixing. The buttery, non-sag consistency facilitates the measuring and mixing of small quantities and enhances applicator production rates.

Limitations: The recommended minimum substrate temperature during installation is 40 deg F. The minimum substrate temperature for cure is 40 deg F. The maximum in-service temperature should not exceed 20 deg F below the HDT in bonding applications subjected to substantial and sustained shear stresses that may cause creep. Do not add solvents or otherwise thin this material. KEMKO 175 has a characteristic amine odor and may be considered for interior applications with adequate ventilation. The cured material exhibits generally poor color stability with moderate discoloring and chalking when exposed to direct sunlight.

Packaging: Standard package size of Part A + Part B is a 3 and 15 gallon unit.

Shelf Life: Three years minimum in unopened, original containers when stored between 60 and 90 deg F in a dry place away from sunlight. Remixing of components may be required upon prolonged storage.

Chemical Resistance: KEMKO 175 has excellent resistance to a wide range of commonly encountered chemicals including acids and bases, aircraft and automotive fluids, petroleum fuels, cutting oils, etc. It has limited resistance to hydrocarbon solvents. Performance is a function of the specific chemical and concentration, ambient and solution temperatures, exposure times and housekeeping procedures. For information on specific chemicals and exposure conditions, contact a ChemCo Systems, Inc., technical representative.

Color Selection: The standard color of the mixed components is translucent amber. Custom colors are available and may require minimum quantities and/or slightly higher cost.

Surface Preparation: Concrete surfaces may be dry, damp or wet (no free standing water) but must be sound and free of all bond-inhibiting substances. Prepare surfaces for bonding in accordance with *ASTM D 4259, "Standard Practice for Abrading Concrete,"* or *ACI 503R, Chapter 5, "Preparing Surfaces for Epoxy Compound Application,"* and ChemCo Systems, Inc.'s specific recommendations. Properly prepared concrete surfaces should have a minimum strength of 250 psi in direct tension. Steel surfaces should be cleaned to "white metal" according to SSPC SP 5.

Mixing: KEMKO 175 is a two-component adhesive. The resin to hardener (Part A : Part B) mix ratio is 2:1, by volume. Use quantities that can be applied before the working life of the mixed material expires. For bonding applications, transfer the appropriate quantities of Part A and Part B into a mixing container. Blend thoroughly using a Jiffy mixer blade attached to a low speed (350 - 750 rpm) electric or pneumatic drill. Proper mixing will take 2 - 3 minutes. For crack sealing, transfer the appropriate quantities of Part A and Part B onto a palette and manually mix with a margin trowel. Wear safety glasses and clean neoprene rubber gloves when handling the material.

Installing: The KIP System™, its products and equipment are only available from KEMKO licensee/applicators. For bonding applications, apply material on both surfaces to be bonded in thickness sufficient to fill all gaps between the two surfaces. Mate the surfaces and apply pressure until excess adhesive is extruded from the joint. Ideally, the material thickness at the bond line should be 1/32 - 1/8 inch. Surfaces must be mated while the adhesive is tacky. Allow for adequate cure of the epoxy adhesive before the bonded section is returned to service. For crack sealing applications, spread a thin layer of KEMKO 175 over the crack taking care to force material into the crack. Allow for adequate cure of the adhesive before beginning pressure injection grouting. For additional information on adhesive bonding, see *ACI 503R, Chapter 7, "Applying Epoxy Compounds."*



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Typical Properties (1)

Property	Test Method	Value
Mix Ratio, A: B,	by vol by wt	2: 1 100: 46
Color:	Part A Part B Mixed	Clear Amber Clear Dark Amber Clear Dark Amber
Weight per Gallon, lb:	Part A Part B Mixed	12.4 11.2 12.0
Viscosity, p:	Part A Part B Mixed	6400 8000 7000
Non-Sag Thickness, inches	ASTM D 2730	1/2
Gel Time, 100 g, minutes: @ 40° F @ 73° F	ASTM D 2471	90 18
Compressive Yield Strength, psi Compressive Modulus, psi	ASTM D 695 ASTM D 695	12,500 550,000
Time To Bond Strength Greater than Mortar, hours @ 73° F (ASTM C 109 Mortar) @ 40° F	ASTM D 4541	18 4
Heat Deflection Temp, deg F	ASTM D 648	130
Wet Slant Shear Strength, psi (Cure schedule, 24 hours @ 73° F)	AASHTO T-237	Cement mortar failure (2)

(1) Cure schedule, 7 days at 73° ± 4° F and test temperature, 73° ± 4° F unless otherwise indicated.

(2) Compressive strength of cement mortar, 4500 psi.

Clean up: All tools and equipment must be cleaned before the mixed material cures. Cleaning can be facilitated with a solvent such as acetone or heavy-duty detergents. Cured material may be removed from equipment and tools by soaking in an epoxy stripper.

Handling and Toxicity: This bulletin does not accompany the product when soil. For hazard warnings, safe handling and first aid instructions, **READ CAREFULLY THE MATERIAL SAFETY DATA SHEETS AND CONTAINER WARNING LABELS.**

Part A: Liquid epoxy resin, HMIS Health Hazard Rating- 2 (Moderate Hazard). Warning! Causes eye and skin irritation. May cause allergic skin reaction. Harmful if swallowed. Avoid contact with eyes, skin and clothing. Wash thoroughly after handling. Avoid prolonged or repeated contact with skin.

Part B: Liquid epoxy hardener, HMIS Health Hazard Rating- 3 (Serious Hazard). Contains alkaline amines. Danger! Causes severe eye and skin burns. May cause allergic skin and respiratory reaction.

Combustible, corrosive. Do not get in eyes or skin or on clothing. Avoid breathing vapor. Keep container closed. Use only with adequate ventilation. Wash thoroughly after handling. Keep away from heat and open flame.

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